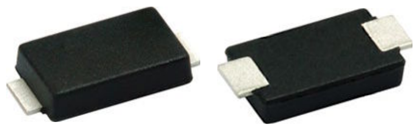
Hyperfast Rectifier, 3 A FRED Pt®

eSMP® Series



Top View   Bottom View

SlimSMA (DO-221AC)

Cathode  Anode

DESIGN SUPPORT TOOLS

click logo to get started

3D Models Available

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3 A
V_R	200 V
V_F at I_F	0.74 V
t_{rr}	30 ns
T_J max.	175 °C
Package	SlimSMA (DO-221AC)
Circuit configuration	Single

FEATURES

- Hyperfast recovery time, reduced Q_{rr}, and soft recovery
- 175 °C maximum operating junction temperature
- Low forward voltage drop
- Low leakage current
- Specific for output and snubber operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT
HALOGEN FREE

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, as high frequency rectifiers and freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		200	V
Average rectified forward current	$I_{F(AV)}$	T_C = 145 °C (1)	3	A
Non-repetitive peak surge current	I_{FSM}	T_J = 25 °C	85	
Operating junction and storage temperatures	T_J, T_{Stg}		-65 to +175	°C

Note

(1) Device on PCB with 8 mm x 16 mm soldering lands

ELECTRICAL SPECIFICATIONS (T_J = 25 °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	I_R = 100 μA	200	-	-	V
Forward voltage	V_F	I_F = 3 A	-	0.86	0.93	
		I_F = 3 A, T_J = 125 °C	-	0.74	0.78	
Reverse leakage current	I_R	V_R = V_R rated	-	-	2	μA
		T_J = 125 °C, V_R = V_R rated	-	1	8	
Junction capacitance	C_T	V_R = 200 V	-	13	-	pF

DYNAMIC RECOVERY CHARACTERISTICS (T_J = 25 °C unless otherwise specified)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNITS**
Reverse recovery time	t_{rr}	I_F = 1.0 A, dI_F/dt = 50 A/μs, V_R = 30 V		-	26	-	ns
		I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A		-	-	30	
		T_J = 25 °C	I_F = 3 A dI_F/dt = 200 A/μs V_R = 160 V	-	18	-	
		T_J = 125 °C		-	26	-	
Peak recovery current	I_{RRM}	T_J = 25 °C		-	2.5	-	A
		T_J = 125 °C		-	4	-	
Reverse recovery charge	Q_{rr}	T_J = 25 °C		-	23	-	nC
		T_J = 125 °C		-	50	-	

THERMAL - MECHANICAL SPECIFICATIONS (T_J = 25 °C unless otherwise specified)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNITS**
Maximum junction and storage temperature range	T_J, T_{Stg}		-65	-	175	°C
Thermal resistance, junction to lead	R_{thJL}	Device mounted on PCB with 8 mm x 16 mm soldering lands	-	8	10	°C/W
Thermal resistance, junction to ambient	R_{thJA}	Device mounted on PCB with 2 mm x 3.5 mm soldering lands	-	91	110	
Approximate Weight			0.032			g
			0.0011			oz.
Marking device		Case style SlimSMA (DO-221AC)	3H2			

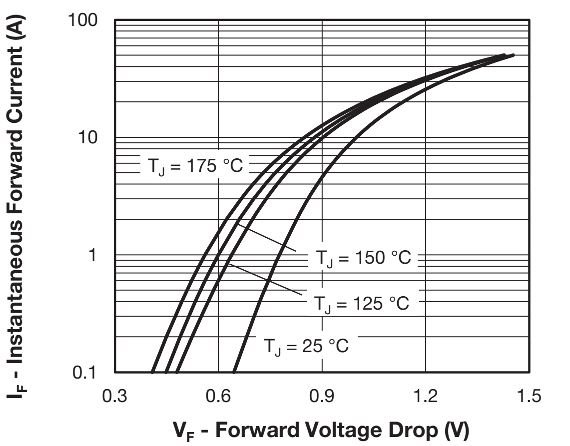


Fig. 1 - Typical Forward Voltage Drop Characteristics

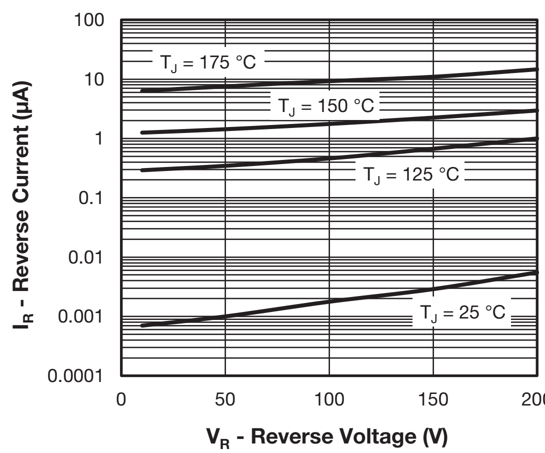


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

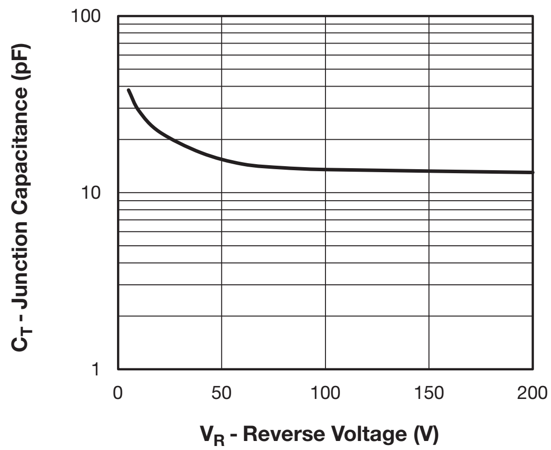


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

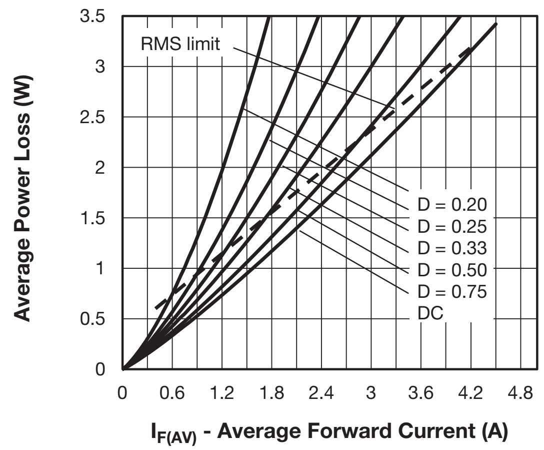


Fig. 5 - Forward Power Loss Characteristics

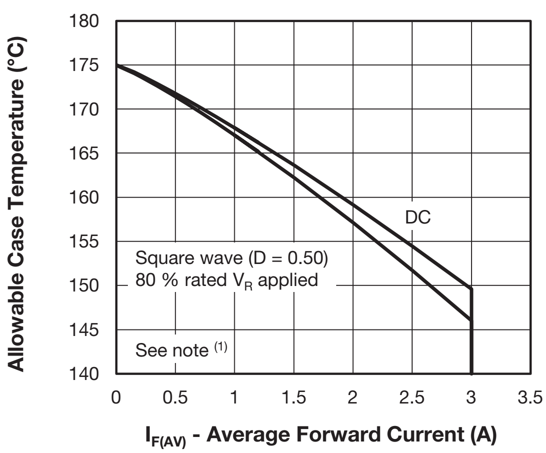


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

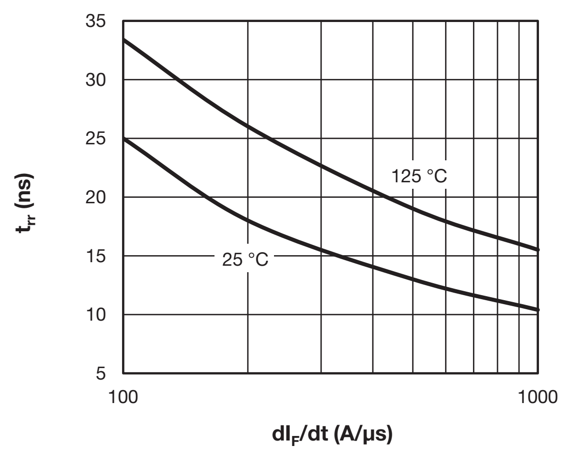


Fig. 6 - Typical Reverse Recovery vs. dI_F/dt

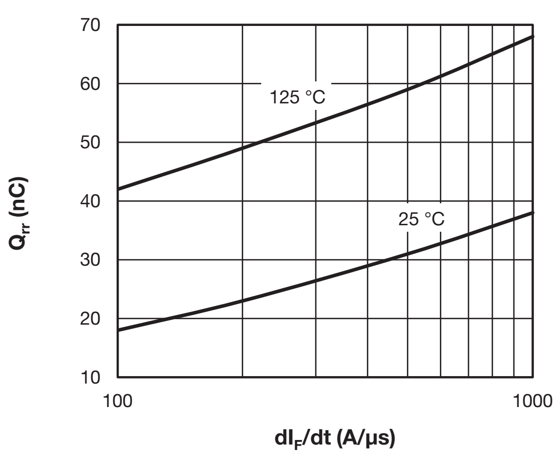


Fig. 7 - Typical Stored Charge vs. dI_F/dt

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see Fig. 6);
Pd_{REV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

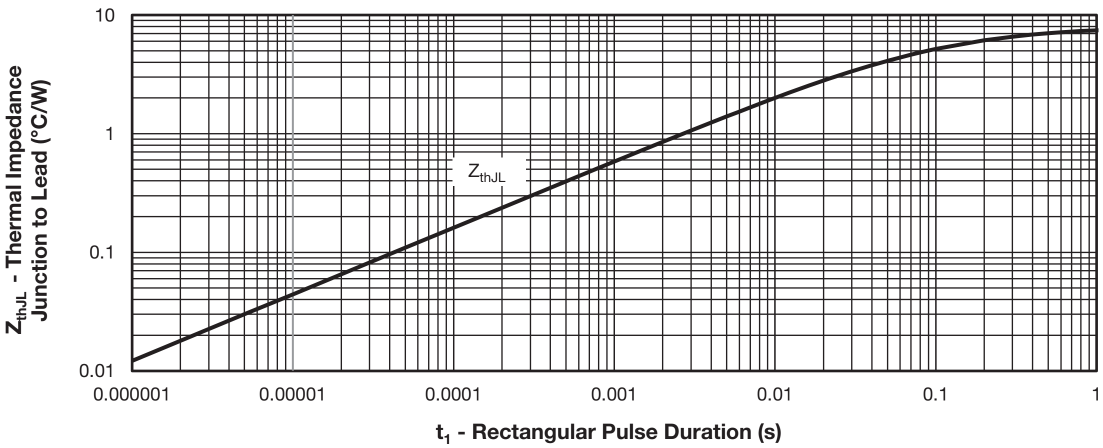


Fig. 8 - Typical Thermal Impedance Z_{thJL} Junction-to-Lead

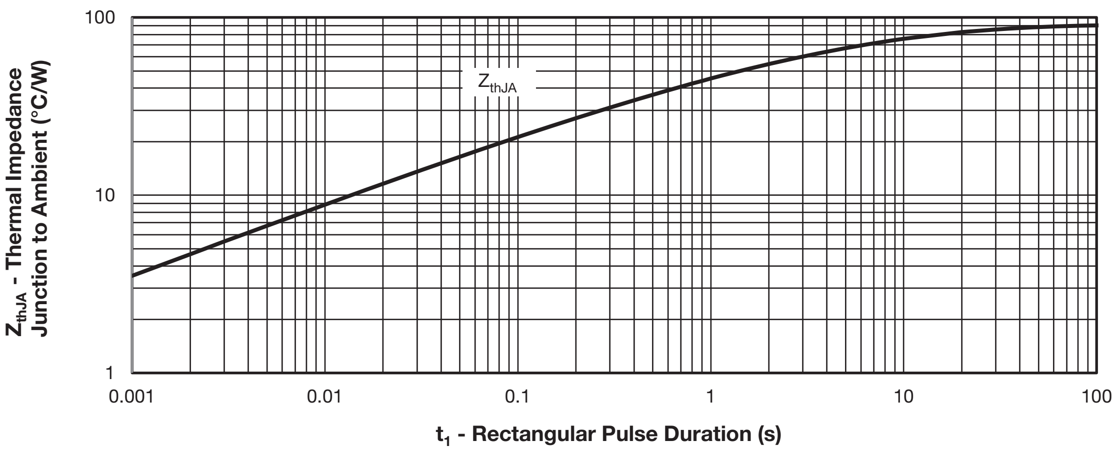
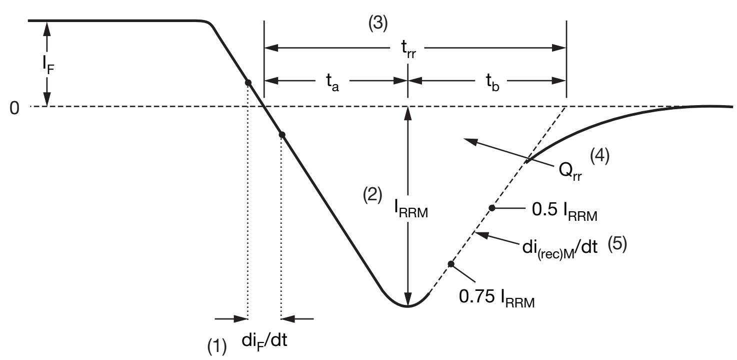


Fig. 9 - Typical Thermal Impedance Z_{thJA} Junction-to-Ambient



(1) di_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	VS-	3	E	J	H	02	-M3
	1	2	3	4	5	6	7

1 - Vishay Semiconductors product

2 - Current rating (3 = 3 A)

3 - Circuit configuration:
E = single diode

4 - J = SlimSMA package

5 - Process type,
H = hyperfast recovery

6 - Voltage code (02 = 200 V)

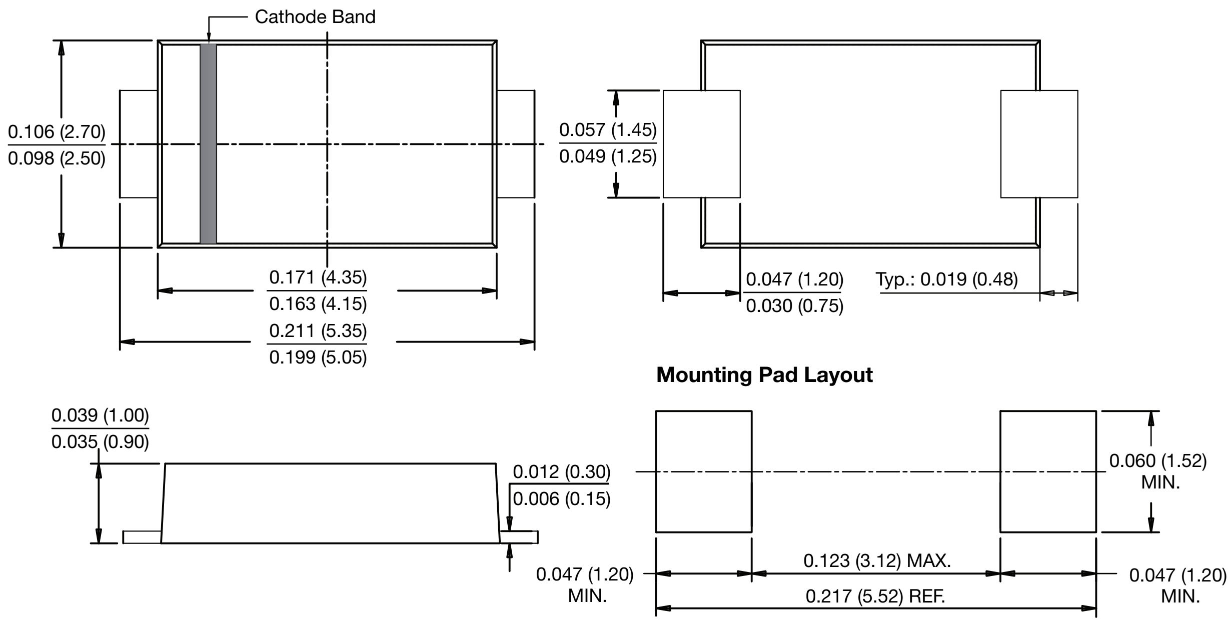
7 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	**QUANTITY PER REEL**	**MINIMUM ORDER QUANTITY**	**PACKAGING DESCRIPTION**
VS-3EJH02-M3/6A	3500	3500	7"diameter plastic tape and reel
VS-3EJH02-M3/6B	14 000	14 000	13"diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95571
Part marking information	www.vishay.com/doc?95562
Packaging information	www.vishay.com/doc?88869

DO-221AC (SlimSMA)

DIMENSIONS in inches (millimeters)



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, “Vishay”), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay’s knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer’s responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer’s technical experts. Product specifications do not expand or otherwise modify Vishay’s terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.